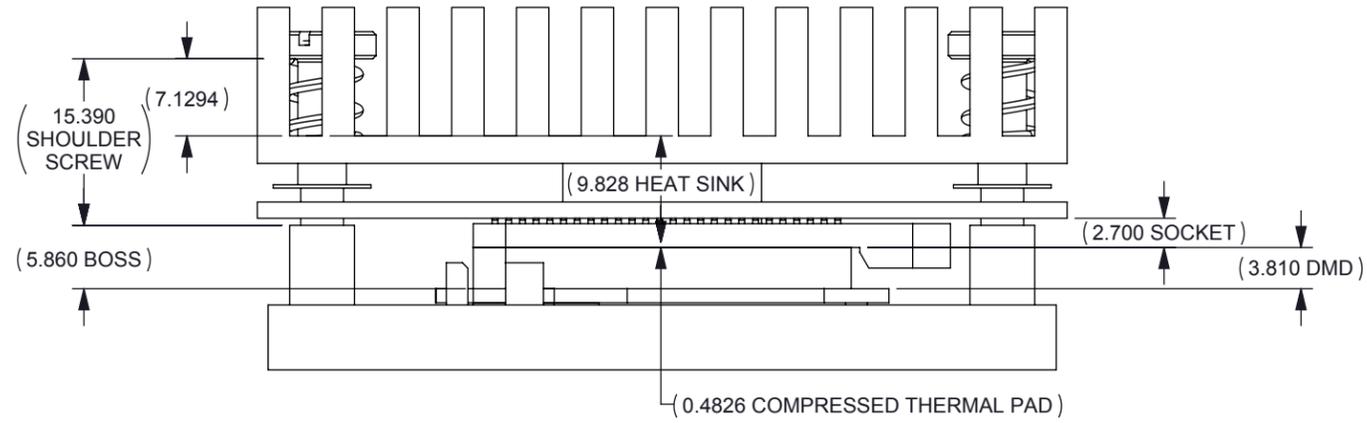
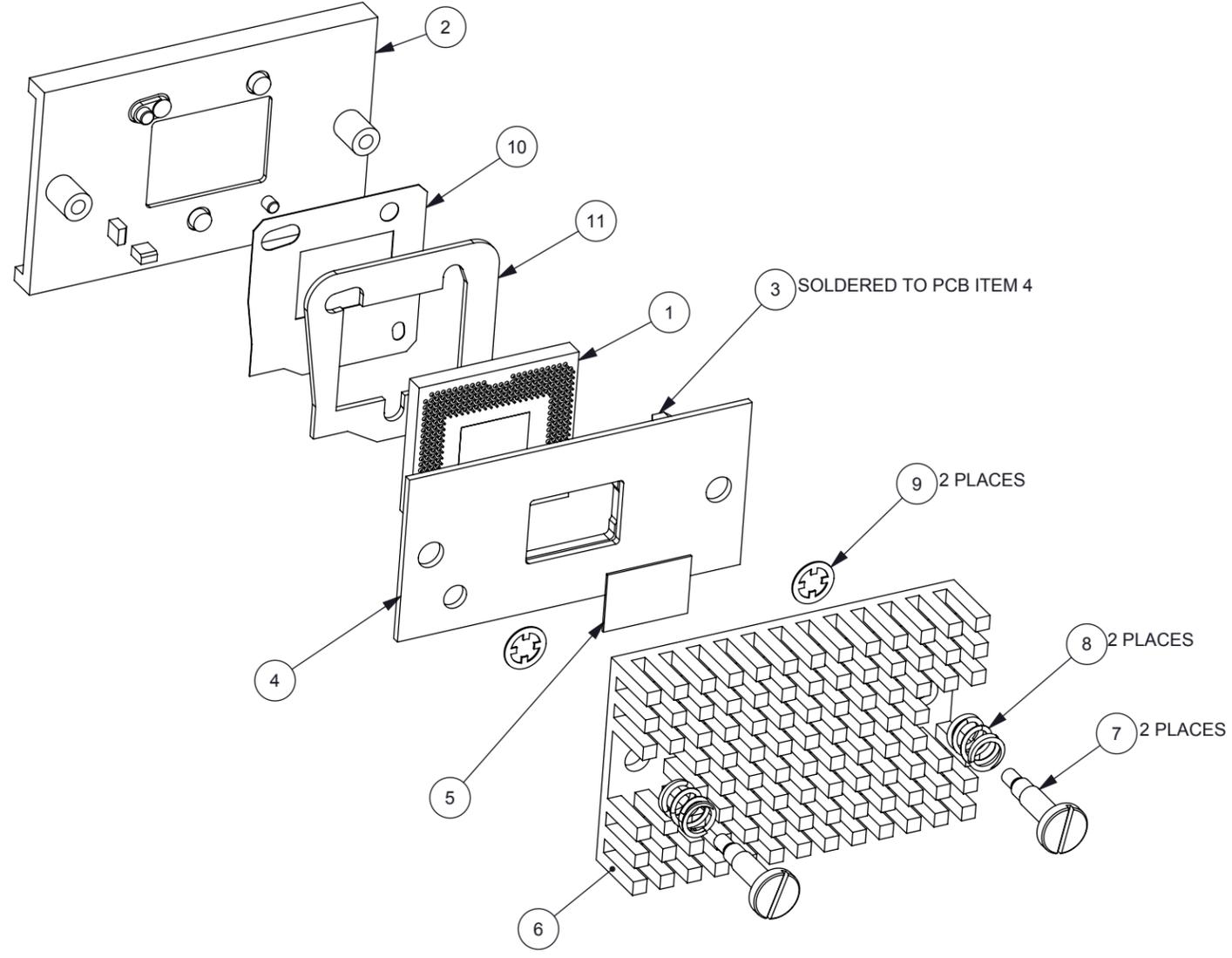
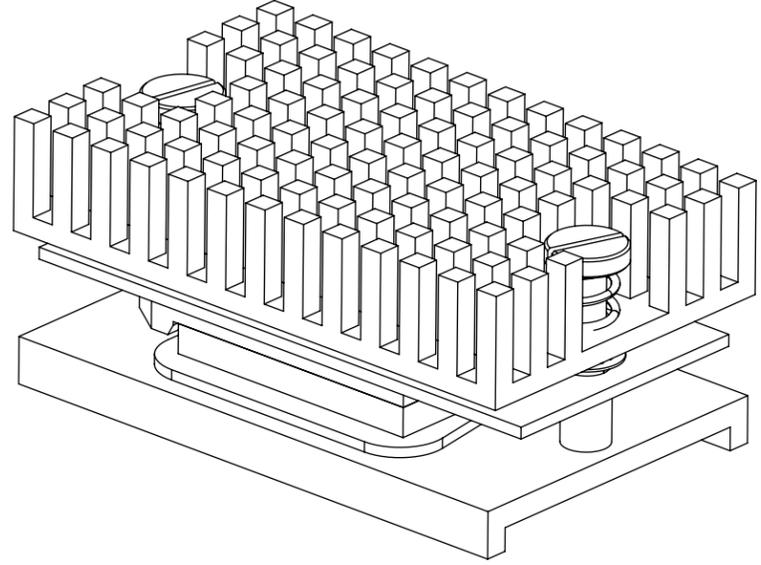


REVISIONS			
REV	DESCRIPTION	DATE	BY
A	INITIAL RELEASE	12/24/2014	JTM

NOTES: UNLESS OTHERWISE SPECIFIED:

- SOME TYPE OF SUPPORT FOR THE DMD PC BOARD IS DESIRED TO ASSURE THE PC BOARD IS SECURED IN POSITION TO MAINTAIN THE DMD ELECTRICAL CONNECTION AFTER MECHANICAL SHOCK AND VIBRATION. SEE TI DRAWING 2507519 FOR CONCEPT IDEAS. CARE SHOULD BE TAKEN TO ENSURE THE METHOD DOES NOT APPLY LOADS TO THE DMD THAT EXCEED SPECIFICATION LIMITS.
- CARE SHOULD BE TAKEN WHEN INSTALLING THE DMD TO NOT DAMAGE THE DMD WINDOW DUE TO THE CLOSE PROXIMITY OF THE ALIGNMENT AND GUIDE FEATURES ON THE INTERFACE.



REF	QTY	ITEM	PART NUMBER	DESCRIPTION	Notes
12		2507519		DMD PC BOARD SUPPORT CONCEPTS	1
1	11	2511728		GASKET, SYSTEM, SERIES 600	
1	10	2511727		APERTURE, SERIES 600 SYSTEM	
2	9	5105-15 (TRUARC)		RETAINER, PUSH NET	
2	8	LC042E01S (LEE SPRING)		SPRING, COIL	
2	7	2511633		SCREW, SHOULDER	
1	6	2511635		HEAT SINK, FEATURE CONCEPT	
1	5	2511634		THERMAL PAD, SERIES 600	
1	4	2511637		ASSEMBLY, PCB, SERIES 600	
1	3	2511569		SOCKET, SERIES 600 ZIF	
1	2	2514396		INTERFACE, SERIES 610 SYSTEM, EDGE GUIDE	
1	1			Series 610 DMD	
QTY	ITEM		PART NUMBER	DESCRIPTION	Notes

UNLESS OTHERWISE SPECIFIED	
• DIMENSIONS ARE IN MILLIMETERS	
• TOLERANCES: ANGLES ±1°	
2 PLACE DECIMALS ±0.25	
1 PLACE DECIMALS ±0.50	
• DIMENSIONAL LIMITS APPLY BEFORE PROCESSES	
• INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994	
• REMOVE ALL BURRS AND SHARP EDGES	
• PARENTHETICAL INFO FOR REF ONLY	
NONE	0314RD
NEXT ASSY	USED ON
APPLICATION	

DWN J. MCKINLEY Engr	DATE 12/23/2014
CQE/QA	
CM	
Apprvd MCKINLEY	DATE 12/23/2014

 <b>SYSTEM INTERFACE CONCEPT</b> <b>ASSEMBLY, EDGE GUIDE, SERIES 610</b>	
SIZE B	DWG NO 2514395
SCALE 2:1	REV A
SHEET 1 OF 2	

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SSZZ031 January 01, 2013

	DWN	DATE	SIZE	DRAWING NO	REV
	J. MCKINLEY	12/23/2014	B	2514395	A
SCALE 2:1			SHEET 2 OF 2		